Photo 109795

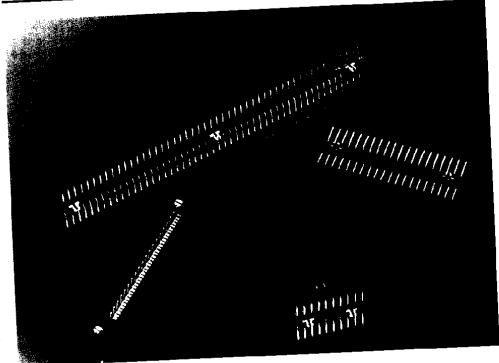


## **AMPMODU System 50 Connectors**

Surface-Mount Connectors, .050 [1.27] Centers, Board-to-Board

## **Product Facts**

- Surface-mount option for parallel board-to-board applications; completely intermateable with AMPMODU System 50 through-hole board-to-board and cable-to-board systems
- Double row, vertical, shrouded header and receptacle assemblies
- Available in select sizes from 10 through 100 positions
- High Density; contacts spaced on .050 x .100 [1.27 x 2.54) centers; compact tootprint
- Compatible with standard surface-mount processes
- Stand-offs for free drainage of flux cleaning solutions; visible solder joints for easy inspection
- Simple, low insertion-force holddown for process retention and long-term strain relief for solder joints
- Available in tape and reel packaging for automatic placement.
- Recognized under the Component Program of Underwriters Laboratories Inc., File No. E28476
- Certified by Canadian Standards Association. File No. LR 7189



The high-density surfacemount connector is another mounling option in the AMPMODU System 50 connector family.

This surface-mount system is totally intermateable with the AMPMODU System 50 thru-hole and cable-toboard connectors.

Additionally, the design of the mating interface has not been changed, ensuring the same high reliability as the thru-hole product.

The surface mount system includes double row, vertical, shrouded header and receptacle assemblies in select sizes from 10 through 100 positions. It meets the tight dimensional requirements of surfacemount technology. The simple, low insertion-force holddown provides both processing retention and long-term strain relief for the solder joints in the headers and receptacles.

AMPMODU System 50 Connectors